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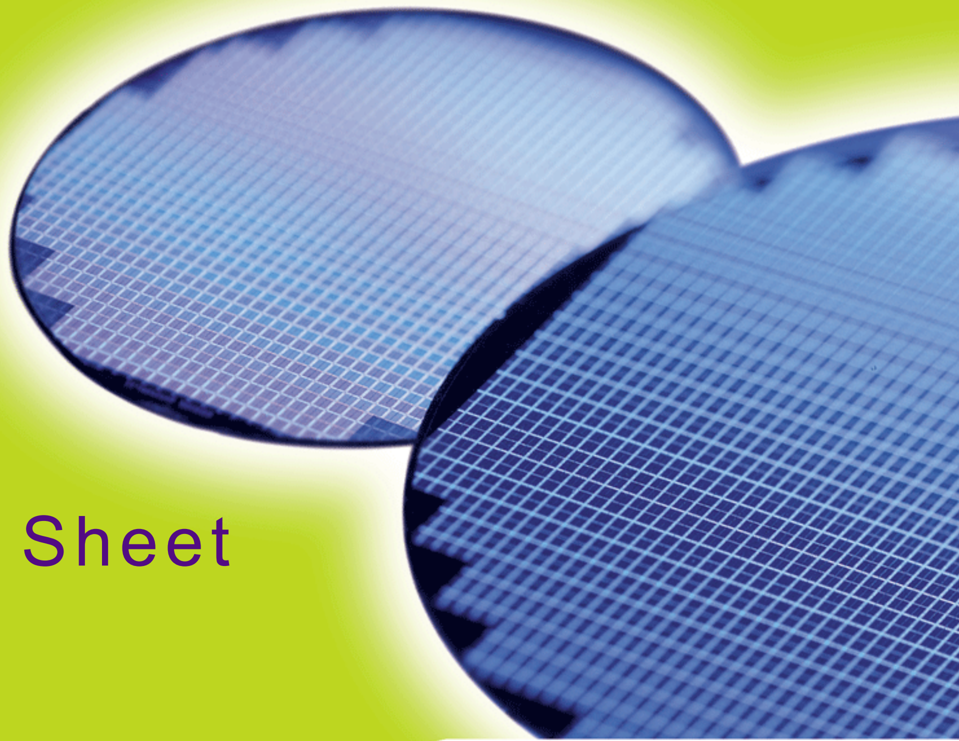
HYS72T512420EFA–[25F/3S]–C

240-Pin Fully-Buffered DDR2 SDRAM Modules
DDR2 SDRAM
RoHS Compliant Products



Internet Data Sheet

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Revision History: Rev.1.20, 2007-10-19	
Page 5	Changed Table 4 “Components on Modules” on Page 5
Page 20	Changed Table 5.1 “I_{CC}/I_{DD} Conditions” on Page 20
Page 20	Changed Table 14 “I_{CC}/I_{DD} Specification for PC2-6400F” on Page 20
Page 65	Changed Table 21 “I_{CC}/I_{DD} Specification for PC2-5300F” on Page 65
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Page 5	Changed Table 2 “Ordering Information for RoHS Compliant Products” on Page 5.
Page 20	Updated Table 5.1 “I_{CC}/I_{DD} Conditions” on Page 20

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1 Overview

This chapter describes the main characteristics of the 240-Pin Fully-Buffered DDR2 SDRAM Modules product family.

1.1 Features

- 240-pin Fully-Buffered ECC Dual-In-Line DDR2 SDRAM Module for PC, Workstation and Server main memory applications.
- two rank 512M × 72 module organization, and 256M × 4, 128M × 4 chip organization
- Standard Double-Data-Rate-Two Synchronous DRAMs (DDR2 SDRAM) with a single + 1.8 V (± 0.1 V) power supply
- 4GB Modules built with chipsize packages PG-TFBGA-60
- Re-drive and re-sync of all address, command, clock and data signals using AMB (Advanced Memory Buffer).
- High-Speed Differential Point-to-Point Link Interface at 1.5 V (Jedec standard pending).
- Host Interface and AMB component industry standard compliant.
- Supports SMBus protocol interface for access to the AMB configuration registers.
- Detects errors on the channel and reports them to the host memory controller.
- Automatic DDR2 DRAM Bus Calibration.
- Automatic Channel Calibration.
- Full Host Control of the DDR2 DRAMs.
- Over-Temperature Detection and Alert.
- Hot Add-on and Hot Remove Capability.
- MBIST and IBIST Test Functions.
- Transparent Mode for DRAM Test Support.
- Low profile: 133.35mm x 30.35 mm
- 240 Pin gold plated card connector with 1.00mm contact centers (JEDEC standard pending).
- Based on JEDEC standard reference card designs (Jedec standard pending).
- SPD (Serial Presence Detect) with 256 Byte serial E^2PROM.Performance:
- RoHS Compliant Products[1)]

TABLE 1
Performance Table

QAG Speed Code			–25F	–3S	Unit
DRAM Speed Grade			DDR2–800D	DDR2–667D	
Module Speed Grade			PC2–6400D	PC2–5300D	
CAS-RCD-RP latencies			5–5–5	5–5–5	
Max. Clock Frequency	CL3	f_{CK3}	200	200	MHz
	CL5	f_{CK5}	400	333	MHz
	CL4	f_{CK4}	266	266	MHz
Min. RAS-CAS-Delay		t_{RCD}	12.5	15	ns
Min. Row Precharge Time		t_{RP}	12.5	15	ns
Min. Row Active Time		t_{RAS}	45	45	ns
Min. Row Cycle Time		t_{RC}	57.5	60	ns

1) RoHS Compliant Product: Restriction of the use of certain hazardous substances (RoHS) in electrical and electronic equipment as defined in the directive 2002/95/EC issued by the European Parliament and of the Council of 27 January 2003. These substances include mercury, lead, cadmium, hexavalent chromium, polybrominated biphenyls and polybrominated biphenyl ethers.

1.2 Description

This document describes the electrical and mechanical features of a 240-pin,PC2-5300F, ECC type, Fully Buffered Double-Data-Rate Two Synchronous DRAM Dual In-Line Memory Modules (DDR2 SDRAM FB-DIMMs). Fully Buffered DIMMs use commodity DRAMs isolated from the memory channel behind a buffer on the DIMM. They are intended for use as main memory when installed in systems such as servers and workstations. PC2-5300F, refers to the DIMM naming convention indicating the DDR2 SDRAMs running at 333, MHz clock speed and offering 5300, MB/s peak bandwidth. FB-DIMM features a novel architecture including the Advanced Memory Buffer. This single chip component, located in the center of each DIMM, acts as a repeater and buffer for all signals and commands which are exchanged between the host controller and the DDR2 SDRAMs including data in- and output. The AMB communicates with the host controller and / or the adjacent DIMMs on a system board using an Industry Standard High-Speed Differential Point-to-Point Link Interface at 1.5 V.

The Advanced Memory Buffer also allows buffering of memory traffic to support large memory capacities. All memory control for the DRAM resides in the host, including memory request initiation, timing, refresh, scrubbing, sparing, configuration access, and power management. The Advanced Memory Buffer interface is responsible for handling channel and memory requests to and from the local DIMM and for forwarding requests to other DIMMs on the memory channel. Fully Buffered DIMM provides a high memory bandwidth, large capacity channel solution that has a narrow host interface. The maximum memory capacity is 288 DDR2 SDRAM devices per channel or 8 DIMMs.

TABLE 2
Ordering Information for RoHS Compliant Products

Product Type[1]	Compliance Code[2]	Description	SDRAM Technology
PC2-6400			
HYS72T512420EFA–25F–C	4GB 2R×4 PC2–6400F–555–11–ZZ	2 Ranks, ECC	1Gbit (×4)
PC2-5300			
HYS72T512420EFA–3S–C	4GB 2R×4 PC2–5300F–555–11–ZZ	2 Ranks, ECC	1Gbit (×4)

1) For detailed information regarding Product Type of Qimonda please see chapter "Product Type Nomenclature" of this datasheet.
2) The Compliance Code is printed on the module label and describes the speed grade, for example "PC2–6400F–555–11–H0" where 6400F means Fully-Buffered DIMM modules with 6.40 GB/sec Module Bandwidth and "555–11" means Column Address Strobe (CAS) latency =5, Row Column Delay (RCD) latency = 5 and Row Precharge (RP) latency = 5 using the latest JEDEC SPD Revision 1.1 and produced on the Raw Card "H".

TABLE 3
Address Format

DIMM Density	Module Organization	Memory Ranks	ECC/ Non-ECC	# of SDRAMs	# of row/bank/column bits	Raw Card
4GB	512M × 72	2	ECC	36	14/3/11	Z

TABLE 4
Components on Modules

Product Type[1)2)]	DRAM Components[1]	DRAM Density	DRAM Organisation
HYS72T512420EFA	HYB18T1G400CF	1Gbit	256M × 4

1) Green Product
2) For a detailed description of all functionalities of the DRAM components on these modules see the component data sheet.

2 Pin Configuration

The pin configuration of the DDR2 SDRAM DIMM is listed by function in **Table 5** (240 pins). The abbreviations used in columns Pin and Buffer Type are explained in **Table 6** and **Table 7** respectively. The pin numbering is depicted in **Figure 1**.

TABLE 5
Pin Configuration of FB-DIMM

Pin#	Name	Pin Type	Buffer Type	Function
Clock Signals				
228	SCK	I	HSDL_15	**System Clock Input, positive line**
229	$\overline{SCK}$	I	HSDL_15	**System Clock Input, negative line**
Control Signals				
17	$\overline{RESET}$	I	LV-CMOS	**AMB reset signal**
Northbound				
22	PN0	O	HSDL_15	**Primary Northbound Data, positive lines**
25	PN1	O	HSDL_15	
28	PN2	O	HSDL_15	
31	PN3	O	HSDL_15	
34	PN4	O	HSDL_15	
37	PN5	O	HSDL_15	
51	PN6	O	HSDL_15	
54	PN7	O	HSDL_15	
57	PN8	O	HSDL_15	
60	PN9	O	HSDL_15	
63	PN10	O	HSDL_15	
66	PN11	O	HSDL_15	
48	PN12	O	HSDL_15	
40	PN13	O	HSDL_15	
23	$\overline{PN0}$	O	HSDL_15	
26	$\overline{PN1}$	O	HSDL_15	
29	$\overline{PN2}$	O	HSDL_15	
32	$\overline{PN3}$	O	HSDL_15	
35	$\overline{PN4}$	O	HSDL_15	
38	$\overline{PN5}$	O	HSDL_15	
52	$\overline{PN6}$	O	HSDL_15	
55	$\overline{PN7}$	O	HSDL_15	
58	$\overline{PN8}$	O	HSDL_15	
61	$\overline{PN9}$	O	HSDL_15	
64	$\overline{PN10}$	O	HSDL_15	

Pin#	Name	Pin Type	Buffer Type	Function
67	$\overline{\text{PN11}}$	O	HSDL_15	
49	$\overline{\text{PN12}}$	O	HSDL_15	
41	$\overline{\text{PN13}}$	O	HSDL_15	
142	SN0	I	HSDL_15	**Secondary Northbound Data, positive lines**
145	SN1	I	HSDL_15	
148	SN2	I	HSDL_15	
151	SN3	I	HSDL_15	
154	SN4	I	HSDL_15	
157	SN5	I	HSDL_15	
171	SN6	I	HSDL_15	
174	SN7	I	HSDL_15	
177	SN8	I	HSDL_15	
180	SN9	I	HSDL_15	
183	SN10	I	HSDL_15	
186	SN11	I	HSDL_15	
168	SN12	I	HSDL_15	
160	SN13	I	HSDL_15	
143	$\overline{\text{SN0}}$	I	HSDL_15	
146	$\overline{\text{SN1}}$	I	HSDL_15	
149	$\overline{\text{SN2}}$	I	HSDL_15	
152	$\overline{\text{SN3}}$	I	HSDL_15	
155	$\overline{\text{SN4}}$	I	HSDL_15	
158	$\overline{\text{SN5}}$	I	HSDL_15	
172	$\overline{\text{SN6}}$	I	HSDL_15	
175	$\overline{\text{SN7}}$	I	HSDL_15	
178	$\overline{\text{SN8}}$	I	HSDL_15	
181	$\overline{\text{SN9}}$	I	HSDL_15	
184	$\overline{\text{SN10}}$	I	HSDL_15	
187	$\overline{\text{SN11}}$	I	HSDL_15	
169	$\overline{\text{SN12}}$	I	HSDL_15	
161	$\overline{\text{SN13}}$	I	HSDL_15	
Southbound				
70	PS0	I	HSDL_15	**Primary Southbound Data, positive lines**
73	PS1	I	HSDL_15	
76	PS2	I	HSDL_15	
79	PS3	I	HSDL_15	
82	PS4	I	HSDL_15	
93	PS5	I	HSDL_15	
96	PS6	I	HSDL_15	
99	PS7	I	HSDL_15	

Pin#	Name	Pin Type	Buffer Type	Function
102	PS8	I	HSDL_15	
90	PS9	I	HSDL_15	
71	$\overline{\text{PS0}}$	I	HSDL_15	**Primary Southbound Data, negative lines**
74	$\overline{\text{PS1}}$	I	HSDL_15	
77	$\overline{\text{PS2}}$	I	HSDL_15	
80	$\overline{\text{PS3}}$	I	HSDL_15	
83	$\overline{\text{PS4}}$	I	HSDL_15	
94	$\overline{\text{PS5}}$	I	HSDL_15	
97	$\overline{\text{PS6}}$	I	HSDL_15	
100	$\overline{\text{PS7}}$	I	HSDL_15	
103	$\overline{\text{PS8}}$	I	HSDL_15	
91	$\overline{\text{PS9}}$	I	HSDL_15	
190	SS0	O	HSDL_15	**Secondary Southbound data, positive lines**
193	SS1	O	HSDL_15	
196	SS2	O	HSDL_15	
199	SS3	O	HSDL_15	
202	SS4	O	HSDL_15	
213	SS5	O	HSDL_15	
216	SS6	O	HSDL_15	
219	SS7	O	HSDL_15	
222	SS8	O	HSDL_15	
210	SS9	O	HSDL_15	
191	$\overline{\text{SS0}}$	O	HSDL_15	**Secondary Southbound data, negative lines**
194	$\overline{\text{SS1}}$	O	HSDL_15	
197	$\overline{\text{SS2}}$	O	HSDL_15	
200	$\overline{\text{SS3}}$	O	HSDL_15	
203	$\overline{\text{SS4}}$	O	HSDL_15	
214	$\overline{\text{SS5}}$	O	HSDL_15	
217	$\overline{\text{SS6}}$	O	HSDL_15	
220	$\overline{\text{SS7}}$	O	HSDL_15	
223	$\overline{\text{SS8}}$	O	HSDL_15	
211	$\overline{\text{SS9}}$	O	HSDL_15	
EEPROM				
120	SCL	I	CMOS	**Serial Bus Clock**
119	SDA	I/O	OD	**Serial Bus Data**
239	SA0	I	CMOS	**Serial Address Select Bus 2:0**
240	SA1	I	CMOS	
118	SA2	I	CMOS	
Power Supplies				

Pin#	Name	Pin Type	Buffer Type	Function
238	V_{DDSPD}	PWR	–	**EEPROM Power Supply**
9,10,12,13,129,130,132,133	V_{CC}	PWR	–	**AMB Core Power / Channel Interface Power**
15,117,135,237	V_{TT}	PWR	–	**Address/Command/Clock Termination Power**
1,2,3,5,6,7,108,109,111,112,113,115,116,121,122,123,125,126,127,231,232,233,235,236	V_{DD}	PWR	–	**Power Supply**
4,8,11,14,18,21,24,27,30,33,36,39,42,43,46,47,50,53,56,59,62,65,68,69,72,75,78,81,84,85,88,89,92,95,98,101,104,107,110,114,124,128,131,134,138,141,144,147,150,153,156,159,162,163,166,167,170,173,176,179,182,185,188,189,192,195,198,201,204,205,208,209,212,215,218,221,224,227,230,234	V_{SS}	GND	–	**Ground Plane**
Other Pins				

Pin#	Name	Pin Type	Buffer Type	Function
19,20,44,45, 86,87,105,106,139, 140,164,165,206,207,225,226	RFU	NC	–	**Not connected** Pins not connected on Infineon FB-DIMM's. Pin positions are reserved for future architecture flexibility.
136	VID0	–	–	**Voltage ID** *Note: These Pins must be unconnected for DDR2-based Fully Buffered DIMMs VID[0] is V_{DD} value: OPEN = 1.8 V, GND = 1.5 V; VID[1] is V_{CC} value: OPEN = 1.5 V, GND = 1.2 V*
16	VID1	–	–	
137	Test	AI	–	**VREF** *Note: Pin must be unconnected for normal operation*

TABLE 6
Abbreviations for Buffer Type

Abbreviation	Description
HSDL_15	High-Speed Differential Point-to-Point Link Interface at 1.5 V
LV-CMOS	Low Voltage CMOS
CMOS	CMOS Levels
OD	Open Drain. The corresponding pin has 2 operational states, active low and tristate, and allows multiple devices to share as a wire-OR.

TABLE 7
Abbreviations for Pin Type

Abbreviation	Description
I	Standard input-only pin. Digital levels.
O	Output. Digital levels.
I/O	I/O is a bidirectional input/output signal.
AI	Input. Analog levels.
PWR	Power
GND	Ground
NU	Not Usable
NC	Not Connected

FIGURE 1
Pin Configuration for FB-DIMM (240 pin)

Front Side Pin	Signal	Back Side Pin	Signal
Pin 001	V_{DD}	Pin 121	V_{DD}
Pin 002	V_{DD}	Pin 122	V_{DD}
Pin 003	V_{DD}	Pin 123	V_{DD}
Pin 004	V_{SS}	Pin 124	V_{SS}
Pin 005	V_{DD}	Pin 125	V_{DD}
Pin 006	V_{DD}	Pin 126	V_{DD}
Pin 007	V_{DD}	Pin 127	V_{DD}
Pin 008	V_{SS}	Pin 128	V_{SS}
Pin 009	V_{CC}	Pin 129	V_{CC}
Pin 010	V_{CC}	Pin 130	V_{CC}
Pin 011	V_{SS}	Pin 131	V_{SS}
Pin 012	V_{CC}	Pin 132	V_{CC}
Pin 013	V_{CC}	Pin 133	V_{CC}
Pin 014	V_{SS}	Pin 134	V_{SS}
Pin 015	V_{TT}	Pin 135	V_{TT}
Pin 016	VID1	Pin 136	VID0
Pin 017	$\overline{RESET}$	Pin 137	TEST
Pin 018	V_{SS}	Pin 138	V_{SS}
Pin 019	NC	Pin 139	NC
Pin 020	NC	Pin 140	NC
Pin 021	V_{SS}	Pin 141	V_{SS}
Pin 022	PN0	Pin 142	SN0
Pin 023	$\overline{PN0}$	Pin 143	$\overline{SN0}$
Pin 024	V_{SS}	Pin 144	V_{SS}
Pin 025	PN1	Pin 145	SN1
Pin 026	$\overline{PN1}$	Pin 146	$\overline{SN1}$
Pin 027	V_{SS}	Pin 147	V_{SS}
Pin 028	PN2	Pin 148	SN2
Pin 029	$\overline{PN2}$	Pin 149	$\overline{SN2}$
Pin 030	V_{SS}	Pin 150	V_{SS}
Pin 031	PN3	Pin 151	SN3
Pin 032	$\overline{PN3}$	Pin 152	$\overline{SN3}$
Pin 033	V_{SS}	Pin 153	V_{SS}
Pin 034	PN4	Pin 154	SN4
Pin 035	$\overline{PN4}$	Pin 155	$\overline{SN4}$
Pin 036	V_{SS}	Pin 156	V_{SS}
Pin 037	PN5	Pin 157	SN5
Pin 038	$\overline{PN5}$	Pin 158	$\overline{SN5}$
Pin 039	V_{SS}	Pin 159	V_{SS}
Pin 040	PN13	Pin 160	SN13
Pin 041	$\overline{PN13}$	Pin 161	$\overline{SN13}$
Pin 042	V_{SS}	Pin 162	V_{SS}
Pin 043	V_{SS}	Pin 163	V_{SS}
Pin 044	NC	Pin 164	NC
Pin 045	NC	Pin 165	NC
Pin 046	V_{SS}	Pin 166	V_{SS}
Pin 047	V_{SS}	Pin 167	V_{SS}
Pin 048	PN12	Pin 168	SN12
Pin 049	$\overline{PN12}$	Pin 169	$\overline{SN12}$
Pin 050	V_{SS}	Pin 170	V_{SS}
Pin 051	PN6	Pin 171	SN6
Pin 052	$\overline{PN6}$	Pin 172	$\overline{SN6}$
Pin 053	V_{SS}	Pin 173	V_{SS}
Pin 054	PN7	Pin 174	SN7
Pin 055	$\overline{PN7}$	Pin 175	$\overline{SN7}$
Pin 056	V_{SS}	Pin 176	V_{SS}
Pin 057	PN8	Pin 177	SN8
Pin 058	$\overline{PN8}$	Pin 178	$\overline{SN8}$
Pin 059	V_{SS}	Pin 179	V_{SS}
Pin 060	PN9	Pin 180	SN9
Pin 061	$\overline{PN9}$	Pin 181	$\overline{SN9}$
Pin 062	V_{SS}	Pin 182	V_{SS}
Pin 063	PN10	Pin 183	SN10
Pin 064	$\overline{PN10}$	Pin 184	$\overline{SN10}$
Pin 065	V_{SS}	Pin 185	V_{SS}
Pin 066	PN11	Pin 186	SN11
Pin 067	$\overline{PN11}$	Pin 187	$\overline{SN11}$
Pin 068	V_{SS}	Pin 188	V_{SS}
Pin 069	V_{SS}	Pin 189	V_{SS}
Pin 070	PS0	Pin 190	SS0
Pin 071	$\overline{PS0}$	Pin 191	$\overline{SS0}$
Pin 072	V_{SS}	Pin 192	V_{SS}
Pin 073	PS1	Pin 193	SS1
Pin 074	$\overline{PS1}$	Pin 194	$\overline{SS1}$
Pin 075	V_{SS}	Pin 195	V_{SS}
Pin 076	PS2	Pin 196	SS2
Pin 077	$\overline{PS2}$	Pin 197	$\overline{SS2}$
Pin 078	V_{SS}	Pin 198	V_{SS}
Pin 079	PS3	Pin 199	SS3
Pin 080	$\overline{PS3}$	Pin 200	$\overline{SS3}$
Pin 081	V_{SS}	Pin 201	V_{SS}
Pin 082	PS4	Pin 202	SS4
Pin 083	$\overline{PS4}$	Pin 203	$\overline{SS4}$
Pin 084	V_{SS}	Pin 204	V_{SS}
Pin 085	V_{SS}	Pin 205	V_{SS}
Pin 086	NC	Pin 206	NC
Pin 087	NC	Pin 207	NC
Pin 088	V_{SS}	Pin 208	V_{SS}
Pin 089	V_{SS}	Pin 209	V_{SS}
Pin 090	PS9	Pin 210	SS9
Pin 091	$\overline{PS9}$	Pin 211	$\overline{SS9}$
Pin 092	V_{SS}	Pin 212	V_{SS}
Pin 093	PS5	Pin 213	SS5
Pin 094	$\overline{PS5}$	Pin 214	$\overline{SS5}$
Pin 095	V_{SS}	Pin 215	V_{SS}
Pin 096	PS6	Pin 216	SS6
Pin 097	$\overline{PS6}$	Pin 217	$\overline{SS6}$
Pin 098	V_{SS}	Pin 218	V_{SS}
Pin 099	PS7	Pin 219	SS7
Pin 100	$\overline{PS7}$	Pin 220	$\overline{SS7}$
Pin 101	V_{SS}	Pin 221	V_{SS}
Pin 102	PS8	Pin 222	SS8
Pin 103	$\overline{PS8}$	Pin 223	$\overline{SS8}$
Pin 104	V_{SS}	Pin 224	V_{SS}
Pin 105	NC	Pin 225	NC
Pin 106	NC	Pin 226	NC
Pin 107	V_{SS}	Pin 227	V_{SS}
Pin 108	V_{DD}	Pin 228	SCK
Pin 109	V_{DD}	Pin 229	$\overline{SCK}$
Pin 110	V_{SS}	Pin 230	V_{SS}
Pin 111	V_{DD}	Pin 231	V_{DD}
Pin 112	V_{DD}	Pin 232	V_{DD}
Pin 113	V_{DD}	Pin 233	V_{DD}
Pin 114	V_{SS}	Pin 234	V_{SS}
Pin 115	V_{DD}	Pin 235	V_{DD}
Pin 116	V_{DD}	Pin 236	V_{DD}
Pin 117	V_{TT}	Pin 237	V_{TT}
Pin 118	SA2	Pin 238	VDDSPD
Pin 119	SDA	Pin 239	SA0
Pin 120	SCL	Pin 240	SA1

FRONT SIDE / BACK SIDE

MPPT0520

3 Basic Functionality

This chapter describes the basic functionality.

3.1 Advanced Memory Buffer Overview

The Advanced Memory Buffer (AMB) reference design complies with the FB-DIMM Architecture and Protocol Specification.

3.2 Advanced Memory Buffer Functionality

The Advanced Memory Buffer will perform the following FB-DIMM channel functions:

- Supports channel initialization procedures as defined in the initialization chapter of the FB-DIMM Architecture and Protocol Specification to align the clocks and the frame boundaries, verify channel connectivity, and identify AMB DIMM position.
- Supports the forwarding of southbound and northbound frames, servicing requests directed to a specific AMB or DIMM, as defined in the protocol chapter, and merging the return data into the northbound frames.
- If the AMB resides on the last DIMM in the channel, the AMB initializes northbound frames.
- Detects errors on the channel and reports them to the host memory controller.
- Support the FB-DIMM configuration register set as defined in the register chapters.
- Acts as DRAM memory buffer for all read, write, and configuration accesses addressed to the DIMM.
- Provides a read buffer FIFO and a write buffer FIFO.
- Supports an SMBus protocol interface for access to the AMB configuration registers.
- Provides logic to support MEMBIST and IBIST Design for Test functions.
- Provides a register interface for the thermal sensor and status indicator.
- Functions as a repeater to extend the maximum length of FB-DIMM Links.

Transparent Mode for DRAM Test Support

In this mode, the Advanced Memory Buffer will provide lower speed tester access to DRAM pins through the FB-DIMM I/O pins. This allows the tester to send an arbitrary test pattern to the DRAMs. Transparent mode only supports a maximum DRAM frequency equivalent to DDR2 400. Transparent mode functionality:

- Reconfigures FB-DIMM inputs from differential high speed link receivers to two single ended lower speed receivers (~200 MHz)
- These inputs directly control DDR2 Command/Address and input data that is replicated to all DRAMs
- Uses low speed direct drive FB-DIMM outputs to bypass high speed Parallel/Serial circuitry and provide test results back to tester

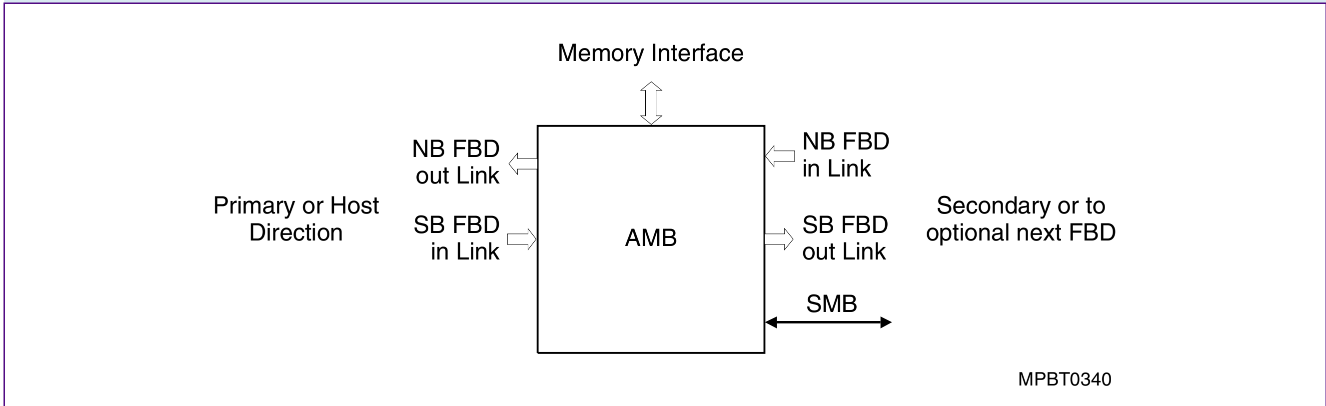
DDR2 SDRAM Interface

- Supports DDR2 at speeds of 667, 800 MT/s
- Supports 256Mb, 512Mb and 1Gb devices in x4 and x8 configurations
- 72-bit DDR2 SDRAM memory array

3.3 Interfaces

Figure 2 illustrates the Advanced Memory Buffer and all of its interfaces. They consist of two FB-DIMM links, one DDR2 channel and an SMBus interface. Each FB-DIMM link connects the Advanced Memory Buffer to a host memory controller or an adjacent FB-DIMM. The DDR2 channel supports direct connection to the DDR2 SDRAMs on a Fully Buffered DIMM.

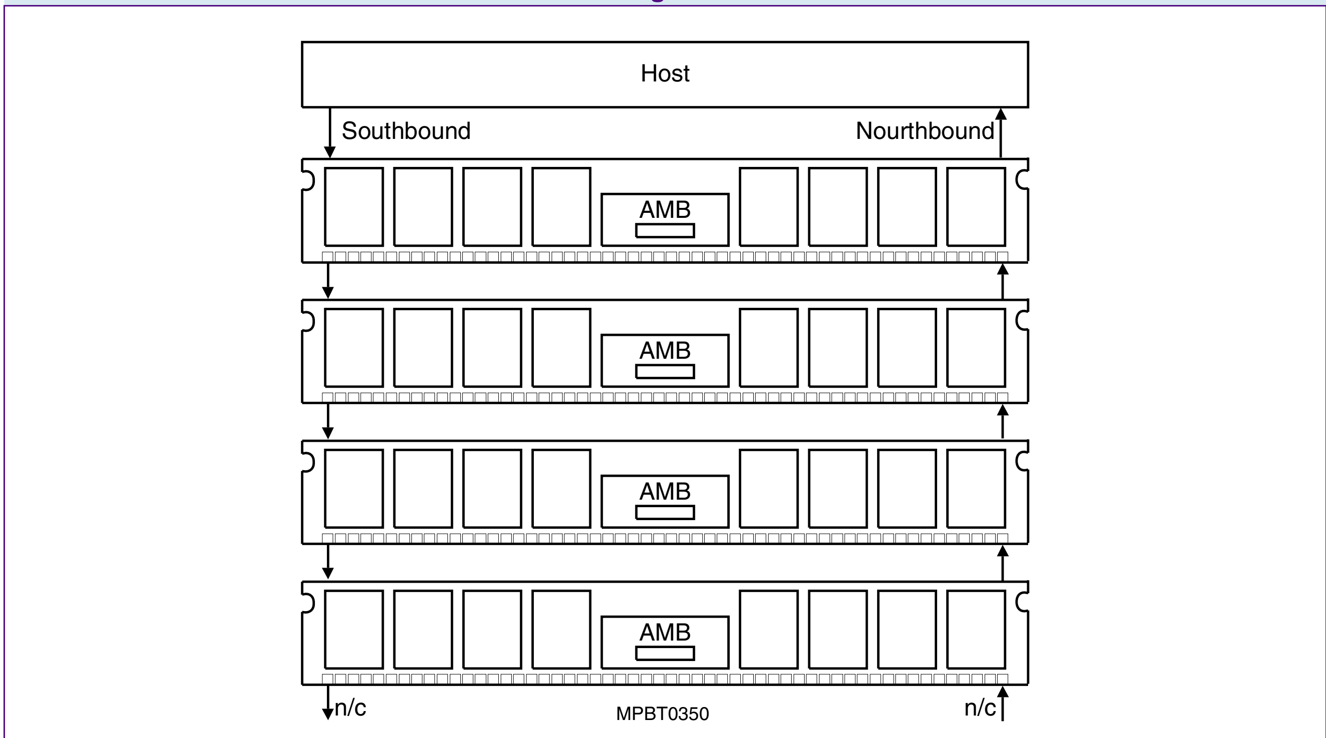
FIGURE 2
Block Diagram Advanced Memory Buffer Interface



Interface Topology

The FB-DIMM channel uses a daisy-chain topology to provide expansion from a single DIMM per channel to up to 8 DIMMs per channel. The host sends data on the southbound link to the first DIMM where it is received and redriven to the second DIMM. On the southbound data path each DIMM receives the data and again re-drives the data to the next DIMM until the last DIMM receives the data. The last DIMM in the chain initiates the transmission of data in the direction of the host (a.k.a. northbound). On the northbound data path each DIMM receives the data and re-drives the data to the next DIMM until the host is reached.

FIGURE 3
Block Diagram of Channel Southbound and Northbound Paths



3.4 High-Speed Differential Point-to-Point Link (at 1.5 V) Interfaces

The Advanced Memory Buffer supports one FB-DIMM Channel consisting of two bidirectional link interfaces using highspeed differential point-to-point electrical signaling. The southbound input link is 10 lanes wide and carries commands and write data from the host memory controller or the adjacent DIMM in the host direction. The southbound output link forwards this same data to the next FB-DIMM. The northbound input link is 14 lanes wide and carries read return data or status information from the next FB-DIMM in the chain back towards the host. The northbound output link forwards this information back towards the host and multiplexes in any read return data or status information that is generated internally. Data and commands sent to the DRAMs travel southbound on 10 primary differential signal line pairs. Data received from the DRAMs and status information travel northbound on 14 primary differential pairs. Data and commands sent to the adjacent DIMM upstream are repeated and travel further southbound on 10 secondary differential pairs. Data and status information received from the adjacent DIMM upstream travel further northbound on 14 secondary differential pairs.

3.4.1 DDR2 Channel

The DDR2 channel on the Advanced Memory Buffer supports direct connection to DDR2 SDRAMs. The DDR2 channel supports two ranks of eight banks with 16 row/column request, 64 data, and eight check-bit signals. There are two copies of address and command signals to support DIMM routing and electrical requirements. Four transfer bursts are driven on the data and check-bit lines at 800 MHz. Propagation delays between read data/check-bit strobe lanes on a given channel can differ. Each strobe can be calibrated by hardware state machines using write/read trial and error. Hardware aligns the read data and check-bits to a single core clock. The Advanced Memory Buffer provides four copies of the command clock phase references (CLK[3:0]) and write data/check-bit strobes (DQSs) for each DRAM nibble.

3.4.2 SMBus Slave Interface

The Advanced Memory Buffer supports an SMBus interface to allow system access to configuration registers independent of the FB-DIMM link. The Advanced Memory Buffer will never be a master on the SMBus, only a slave. Serial SMBus data transfer is supported at 100 kHz. SMBus access to the Advanced Memory Buffer may be a requirement to boot and to set link strength, frequency and other parameters needed to insure robust configurations. It is also required for diagnostic support when the link is down. The SMBus address straps located on the DIMM connector are used by the unique ID.

3.4.3 Channel Latency

FB-DIMM channel latency is measured from the time a read request is driven on the FB-DIMM channel pins to the time when the first 16 bytes (2nd chunk) of read completion data is sampled by the memory controller. When not using the Variable Read Latency capability, the latency for a specific DIMM on a channel is always equal to the latency for any other DIMM on that channel. However, the latency for each DIMM in a specific configuration with some number of DIMMs installed may not be equal to the latency for each FB-DIMM in a configuration with some different number of DIMMs installed. As more DIMMs are added to the channel, additional latency is required to read from each DIMM on the channel. Because the channel is based on the point-to-point interconnection of buffer components between DIMMs, memory requests are required to travel through N-1 buffers before reaching the Nth buffer. The result is that a 4 DIMM channel configuration will have greater idle read latency compared to a 1 DIMM channel configuration. The Variable Read Latency capability can be used to reduce latency for DIMMs closer to the host. The idle latencies listed in this section are representative of what might be achieved in typical AMB designs. Actual implementations with latencies less than the values listed will have higher application performance and vice versa.

3.4.4 Peak Theoretical Channel Throughput

An FB-DIMM channel transfers read completion data on the Northbound data connection. 144 bits of data are transferred for every Northbound data frame. This matches the 18-byte data transfer of an ECC DDR DRAM in a single DRAM command clock. A DRAM burst of 8 from a single channel or a DRAM burst of four from two lock stepped channels provides a total of 72 bytes of data (64 bytes plus 8 bytes ECC). The FB-DIMM frame rate matches the DRAM command clock because of the fixed 6:1 ratio of the FB-DIMM channel clock to the DRAM command clock. Therefore, the Northbound data connection will exhibit the same peak theoretical throughput as a single DRAM channel. For example, when using DDR2 533 DRAMs, the peak theoretical bandwidth of the Northbound data connection is 4.267 GB/sec. Write data is transferred on the Southbound command and data connection, via Command+Wdata frames. 72 bits of data are transferred for every Command+Wdata frame. Two Command+Wdata frames match the 18-byte data transfer of an ECC DDR DRAM in a single DRAM command clock. A DRAM burst of 8 transfers from a single channel, or a burst of 4 from two lock-step channels provides a total of 72 bytes of data (64 bytes plus 8 bytes ECC). When the frame rate matches the DRAM command clock, the Southbound command and data connection will exhibit one half the peak theoretical throughput of a single DRAM channel. For example, when using DDR2 533 DRAMs, the peak theoretical bandwidth of the Southbound command and data connection is 2.133 GB/sec. The total peak theoretical throughput for a single FB-DIMM channel is defined as the sum of the peak theoretical throughput of the Northbound data connection and the Southbound command and data connection. When the frame rate matches the DRAM command clock, this is equal to 1.5 times the peak theoretical throughput of a single DRAM channel. For example, when using DDR2 533 DRAMs, the peak theoretical throughput of a single DDR2-533 channel would be 4.267 GB/sec., while the peak theoretical throughput of the entire FB-DIMM PC4200F channel would be 6.4GB/sec.

3.5 Hot-add

The FB-DIMM channel does not provide a mechanism to automatically detect and report the addition of a new DIMM south of the currently active last DIMM. It is assumed the system will be notified through some means of the addition of one or more new DIMMs so that specific commands can be sent to the host controller to initialize the newly added DIMM(s) and perform a Hot-Add Reset to bring them into the channel timing domain. It should be noted that the power to the DIMM socket must be removed before a “hot-add” DIMM is inserted or removed. Applying or removing the power to a DIMM socket is a system platform function.

3.6 Hot-remove

In order to accomplish removal of DIMMs the host must perform a Fast Reset sequence targeted at the last DIMM that will be retained on the channel. The Fast Reset re-establish the appropriate last DIMM so that the Southbound Tx outputs of the last active DIMM and the Southbound and Northbound outputs of the DIMMs beyond the last active DIMM are disabled. Once the appropriate outputs are disabled the system can coordinate the procedure to remove power in preparation for physical removal of the DIMM if needed. It should be noted that the power to the DIMM socket must be removed before a “hot-add” DIMM is inserted or removed. Applying or removing the power to a DIMM socket is a system platform function.

3.7 Hot-replace

Hot replace of DIMM is accomplished through combining the Hot-Remove and Hot-Add process.

4 Electrical Characteristics

This chapter describes the electrical characteristics.

4.1 Operating Conditions

This chapter describes the operating conditions.

TABLE 8
Absolute Maximum Ratings

Parameter	Symbol	Rating		Unit	Notes
		Min.	Max.		
Voltage on any SMbus interface signal pin relative to V_{SS}	V_{IN}, V_{OUT}	–0.5	+4.00	V	1)
Voltage on V_{DD} pin relative to V_{SS}	V_{DD}	–0.5	+2.4	V	2)
Voltage on V_{CC} pin relative to V_{SS}	V_{CC}	–0,3	+1.75	V	–
Voltage on V_{DDQ} pin relative to V_{SS}	V_{DDQ}	–0.5	+2.3	V	2)3)
Voltage on V_{DDL} pin relative to V_{SS}	V_{DDL}	–0.5	+2.3	V	2)3)
Voltage on any pin relative to V_{SS}	V_{IN}, V_{OUT}	–0.3	+1.75	V	2)
Voltage on V_{TT} pin relative to V_{SS}	V_{TT}	–0.5	+2.3	V	–
Storage Temperature	T_{STG}	–55	+100	°C	2)3)

1) Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
2) When V_{DD} and V_{DDQ} and V_{DDL} are less than 500 mV; V_{REF} may be equal to or less than 300 mV.
3) Storage Temperature is the case surface temperature on the center/top side of the DRAM.

Attention: Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

TABLE 9
Operating Temperature Range

Parameter	Symbol	Values		Unit	Note
		Min	Max		
Junction Temperature	T_J	0	115	°C	1)2)
DRAM Component Case Temperature Range	T_{CASE}	0	95	°C	3)4)
AMB Component Case Temperature Range		0	111	°C	1)2)

1) Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
2) Within the DRAM Component Case temperature range all DRAM specifications will be supported.

3) Self-Refresh period is hard-coded in the DRAMs and therefore it is imperative that the system ensures the DRAM is below 85 °C case temperature before initiating self-refresh operation.
4) Above 85 °C DRAM case temperature the Auto-Refresh command has to be reduced to t_{REFI} = 3.9 µs.

TABLE 10
Supply Voltage Levels and DC Operating Conditions

Parameter	Symbol	Limit Values			Unit	Notes
		Min.	Nom.	Max.		
AMB Supply Voltage DC	V_{CC}	1.455	1.5	1.575	V	1)
AMB Supply Voltage DC + AC		1.425	1.5	1.590	V	2)
DRAM Supply Voltage	V_{DD}	1.7	1.8	1.9	V	–
Termination Voltage	V_{TT}	0.48 × V_{DD}	0.50 × V_{DD}	0.52 × V_{DD}	V	–
EEPROM Supply Voltage	V_{DDSPD}	3.0	3.3	3.6	V	–
DC Input Logic High(SPD)	$V_{IH(DC)}$	2.1	—	V_{DDSPD}	V	3)
DC Input Logic Low(SPD)	$V_{IL(DC)}$	—	—	0.8	V	3)
DC Input Logic High(RESET)	$V_{IH(DC)}$	1.0	—	—	V	4)
DC Input Logic Low(RESET)	$V_{IL(DC)}$	—	—	+0.5	V	3)
Leakage Current (RESET)	I_L	–90	—	+90	µA	4)
Leakage Current (Link)	I_L	–5	—	+5	µA	5)

1) At 0KHz - 30KHz
2) AT 30KHz - 1 MHz
3) Applies for SMB and SPD Bus Signals
4) Applies for AMB CMOS Signal RESET
5) For all other AMB related DC parameters, please refer to the High Speed Differential Link Interface Specifications

TABLE 11
FB-DIMM Latency Range

Parameter	DDR2–800D			DDR2–667D			Unit	Note
	Min.	Nom.	Max.	Min.	Typ.	Max.		
t_{C2D_DIMM}	Tbd	19.35	Tbd	17.5	21	21.5	ns	1)2)
$t_{RESAMPLE_DIMM_SB}$	Tbd	1.68	Tbd	1.4	1.69	2.4	ns	2)3)
$t_{RESAMPLE_DIMM_NB}$	Tbd	1.48	Tbd	1.3	1.73	2.3	ns	2)4)
$t_{RESYNC_DIMM_SB}$	Tbd	2.66	Tbd	2.5	2.8	3.7	ns	2)5)
$t_{RESYNC_DIMM_NB}$	Tbd	2.54	Tbd	2.4	2.8	3.6	ns	2)6)

1) For DDR-800D and DDR-800E no Jedec Standart values are avalible for Min. and Max parameter.
2) Measured delay at FBDIMM gold finger between the center of the1st UI of command frame on the primary southbound lane 81 (connector pins 102 & 103) and the center of the 1st UI of return data on the primary northbound lane 0 (connector pins 22 & 23) – [CL (DRAM CAS latency) value] * [frame clock period – AL (DRAM additional latency) value * frame clock period].
3) Measured delay at FBDIMM gold finger between the center of the 1st UI of a frame on the primary southbound lane 8 (connector pins 102 & 103) and the center of the 1st UI of the same frame on the secondary southbound lane 8 (connector pins 222 & 223).
4) Measured delay at FBDIMM gold finger between the center of the 1st UI of a frame on the secondary northbound lane 0 (connector pins 142 & 143) and the center of the 1st UI of the same frame on the primary northbound lane 0 (connector pins 22 & 23).
5) Measured delay at FBDIMM gold finger between the center of the 1st UI of a frame on the secondary northbound lane 0 (connector pins 142 & 143) and the center of the 1st UI of the same frame on the primary northbound lane 0 (connector pins 22 & 23).

6) Measured delay at FBDIMM gold finger between the center of the1st UI of command frame on the primary southbound lane 81 (connector pins 102 & 103) and the center of the 1st UI of return data on the primary northbound lane 0 (connector pins 22 & 23) – [CL (DRAM CAS latency) value] * [frame clock period – AL (DRAM additional latency) value * frame clock period].

TABLE 12
Environmental Parameters

Parameter	Symbol	Rating	Units	Notes
Operating Temperature	T_{OPR}	See Note		1)
Operating Humidity (relative)	H_{OPR}	10 to 90	%	2)
Storage Temperature	T_{STG}	-50 to +100	°C	2)
Storage Humidity (without condensation)	H_{STG}	5 to 95	%	2)
Barometric pressure (operating)	P_{BAR}	3050	m	2)
Barometric pressure (storage)	P_{BAR}	14240	m	2)

1) The designer must meet the case temperature specifications for individual module components.
2) Stresses greater than those listed may cause permanent damage to the device. This is a stress rating only and the device funcional operation at or above the conditions indicated is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

5 Current Spec. and Conditions

The following table provides an overview of the measurement conditions.

TABLE 13
I_{DD} Measurement Conditions

Parameter	Symbol
Idle Current, single or last DIMM L0 state, idle (0 BW) Primary channel enabled, Secondary channel disabled CKE high. Command and address lines stable. DRAM clock active	$I_{CC_Idle_0}$ $I_{DD_Idle_0}$
Idle Current, first DIMM L0 state, idle (0 BW) Primary and Secondary channels enabled. CKE high. Command and address lines stable. DRAM clock active	$I_{CC_Idle_1}$ $I_{DD_Idle_1}$
Active Power L0 state 50% DRAM BW, 67% read, 33% write. Primary and Secondary channels enabled. DRAM clock active, CKE high.	$I_{CC_Active_1}$ $I_{DD_Active_1}$
Training Primary and Secondary channels enabled. 100% toggle on all channels lanes. DRAMs idle (0 BW). CKE high. Command and address lines stable. DRAM clock active.	$I_{CC_Training}$ $I_{DD_Training}$
IBIST Over all IBIST modesDRAM Idle (0 BW)Primary channel EnabledSecondary channel EnabledCKE high. Command and Address lines stableDRAM clock active	I_{CC_IBIST} I_{DD_IBIST}
MemBIST Over all MemBIST modes >50% DRAM BW (as dictated by the AMB)Primary channel EnabledSecondary channel EnabledCKE high. Command and Address lines stableDRAM clock active	$I_{CC_MEMBIST}$ $I_{DD_MEMBIST}$
Electrical Idle DRAM Idle (0 BW)Primary channel DisabledSecondary channel DisabledCKE low. Command and Address lines FloatedDRAM clock active, ODT and CKE driven low	I_{CC_EI} I_{DD_EI}

Notes

1. *Primary channel Drive strength at 100 % with De-emphasis at -6.5 dB*
2. *Secondary channel drive strength at 60 % with De-emphasis at -3 dB when enabled.*
3. *Address and Data fields provide a 50 % toggle rate on DRAM data and link lanes.*
4. *Burst Length = 4.*
5. *10 lanes southbound and 14 lanes northbound are enabled and active (12 lanes NB if non-ECC DIMM).*
6. *Modeled with 27 Ω termination for command, address, and clocks, and 47 Ω termination for control.*
7. *Termination is referenced to $V_{TT} = V_{DD} / 2$.*

5.1 I_{CC}/I_{DD} Conditions

In the following table you can find the Measurement Conditions and Power Supply Currents.

TABLE 14
I_{CC}/I_{DD} Specification for PC2-6400F

Product Type	HYS72T512420EFA-25F-C	Unit	Note
Speed Grade	PC2-6400F		
Symbol	Typ.		
$I_{CC_Idle_0}$	1.84	A	
$P_{CC_Idle_0}$	2.77	W	
$I_{DD_Idle_0}$	2.47	A	
$P_{DD_Idle_0}$	4.43	W	
$I_{TOT_Idle_0}$	4.41	A	
$P_{TOT_Idle_0}$	7.3	W	
$I_{CC_Idle_1}$	3	A	
$P_{CC_Idle_1}$	4.49	W	
$I_{DD_Idle_1}$	2.31	A	
$P_{DD_Idle_1}$	4.16	W	
$I_{TOT_Idle_1}$	5.37	A	
$P_{TOT_Idle_1}$	8.7	W	
$I_{CC_Active_1}$	3.16	A	
$P_{CC_Active_1}$	4.72	W	
$I_{DD_Active_1}$	4.03	A	
$P_{DD_Active_1}$	7.27	W	
$I_{TOT_Active_1}$	7.28	A	
$P_{TOT_Active_1}$	12.07	W	
I_{CC_IBIST}	3.67	A	
P_{CC_IBIST}	5.46	W	
I_{DD_IBIST}	2.16	A	
P_{DD_IBIST}	3.9	W	
I_{TOT_IBIST}	5.9	A	
P_{TOT_IBIST}	9.43	W	
$I_{CC_Training}$	3.4	A	
$P_{CC_Training}$	5.07	W	
$I_{DD_Trainig}$	2.16	A	
$P_{DD_Training}$	3.9	W	
$I_{TOT_Trainig}$	5.63	A	
$P_{TOT_Training}$	9.04	W	
I_{CC_EI}	2.39	A	
P_{CC_EI}	3.6	W	

Product Type	**HYS72T512420EFA-25F-C**	**Unit**	**Note**
Speed Grade	**PC2-6400F**		
Symbol	**Typ.**		
I_{DD_EI}	0.29	A	
P_{DD_EI}	0.52	W	
I_{TOT_EI}	2.78	A	
P_{TOT_EI}	4.2	W	
$I_{CC_MEMBIST}$	3.24	A	
$P_{CC_MEMBIST}$	4.84	W	
$I_{DD_MEMBIST}$	4.86	A	
$P_{DD_MEMBIST}$	8.77	W	
$I_{TOT_MEMBIST}$	8.13	A	
$P_{TOT_MEMBIST}$	13.64	W	

TABLE 15
I_{CC}/I_{DD} Specification for PC2-5300F

Product Type	HYS72T512420EFA-3S-C	Unit	Note
Speed Grade	PC2-5300F		
Symbol	Typ.		
$I_{CC_Idle_0}$	1.65	A	
$P_{CC_Idle_0}$	2.5	W	
$I_{DD_Idle_0}$	2.35	A	
$P_{DD_Idle_0}$	4.15	W	
$I_{TOT_Idle_0}$	4.08	A	
$P_{TOT_Idle_0}$	6.72	W	
$I_{CC_Idle_1}$	2.66	A	
$P_{CC_Idle_1}$	3.97	W	
$I_{DD_Idle_1}$	2.12	A	
$P_{DD_Idle_1}$	3.73	W	
$I_{TOT_Idle_1}$	4.83	A	
$P_{TOT_Idle_1}$	7.75	W	
$I_{CC_Active_1}$	2.81	A	
$P_{CC_Active_1}$	4.19	W	
$I_{DD_Active_1}$	3.72	A	
$P_{DD_Active_1}$	6.52	W	
$I_{TOT_Active_1}$	6.61	A	
$P_{TOT_Active_1}$	10.78	W	
I_{CC_IBIST}	3.21	A	
P_{CC_IBIST}	4.77	W	
I_{DD_IBIST}	2	A	
P_{DD_IBIST}	3.53	W	
I_{TOT_IBIST}	5.27	A	
P_{TOT_IBIST}	8.35	W	
$I_{CC_Training}$	2.99	A	
$P_{CC_Training}$	4.45	W	
$I_{DD_Trainig}$	2	A	
$P_{DD_Training}$	3.53	W	
$I_{TOT_Trainig}$	5.05	A	
$P_{TOT_Training}$	8.03	W	
I_{CC_EI}	2.08	A	
P_{CC_EI}	3.13	W	
I_{DD_EI}	0.29	A	
P_{DD_EI}	0.5	W	
I_{TOT_EI}	2.47	A	

Product Type	**HYS72T512420EFA-3S-C**	**Unit**	**Note**
Speed Grade	**PC2-5300F**		
Symbol	**Typ.**		
P_{TOT_EI}	3.72	W	
$I_{CC_MEMBIST}$	2.85	A	
$P_{CC_MEMBIST}$	4.26	W	
$I_{DD_MEMBIST}$	4.32	A	
$P_{DD_MEMBIST}$	7.59	W	
$I_{TOT_MEMBIST}$	7.2	A	
$P_{TOT_MEMBIST}$	11.87	W	

6 SPD Codes

This chapter lists all hexadecimal byte values stored in the EEPROM of the products described in this data sheet. SPD stands for serial presence detect. All values with XX in the table are module specific bytes which are defined during production.

List of SPD Code Tables

- **Table 16 "PC2–6400–666" on Page 24**
- **Table 17 "PC2–5300–555" on Page 28**

TABLE 16
PC2–6400–666

Product Type		HYS72T512420EFA–25F–C
Organization		4 GByte
		×72
		2 Ranks (×4)
Label Code		PC2–6400F–555
JEDEC SPD Revision		Rev. 1.1
Byte#	**Description**	**HEX**
0	SPD Size CRC / Total / Used	92
1	SPD Revision	11
2	Key Byte / DRAM Device Type	09
3	Voltage Level of this Assembly	12
4	SDRAM Addressing	49
5	Module Physical Attributes	23
6	Module Type	07
7	Module Organization	10
8	Fine Timebase (FTB) Dividend and Divisor	00
9	Medium Timebase (MTB) Dividend	01
10	Medium Timebase (MTB) Divisor	04
11	$t_{CK.MIN}$ (min. SDRAM Cycle Time)	0A
12	$t_{CK.MAX}$ (max. SDRAM Cycle Time)	20
13	CAS Latencies Supported	43
14	$t_{CAS.MIN}$ (min. CAS Latency Time)	32
15	Write Recovery Values Supported (WR)	52
16	$t_{WR.MIN}$ (Write Recovery Time)	3C
17	Write Latency Times Supported	92
18	Additive Latency Times Supported	60
19	$t_{RCD.MIN}$ (min. RAS# to CAS# Delay)	32
20	$t_{RRD.MIN}$ (min. Row Active to Row Active Delay)	1E

Product Type		**HYS72T512420EFA–25F–C**
Organization		**4 GByte**
		×72
		2 Ranks (×4)
Label Code		**PC2–6400F–555**
JEDEC SPD Revision		**Rev. 1.1**
Byte#	**Description**	**HEX**
21	$t_{RP.MIN}$ (min. Row Precharge Time)	32
22	t_{RAS} and t_{RC} Extension	00
23	$t_{RAS.MIN}$ (min. Active to Precharge Time)	B4
24	$t_{RC.MIN}$ (min. Active to Active / Refresh Time)	D2
25	$t_{RFC.MIN}$ LSB (min. Refresh Recovery Time Delay)	FE
26	$t_{RFC.MIN}$ MSB (min. Refresh Recovery Time Delay)	01
27	$t_{WTR.MIN}$ (min. Internal Write to Read Cmd Delay)	1E
28	$t_{RTP.MIN}$ (min. Internal Read to Precharge Cmd Delay)	1E
29	Burst Lengths Supported	03
30	Terminations Supported	07
31	Drive Strength Supported	01
32	t_{REFI} (avg. SDRAM Refresh Period)	C2
33	$T_{CASE.MAX}$ Delta / ΔT_{4R4W} Delta	57
34	Psi(T-A) DRAM	60
35	ΔT_0 (DT0) DRAM	5C
36	ΔT_{2Q} (DT2Q) DRAM	29
37	ΔT_{2P} (DT2P) DRAM	2B
38	ΔT_{3N} (DT3N) DRAM	2E
39	ΔT_{4R} (DT4R) / ΔT_{4R4W} Sign (DT4R4W) DRAM	4E
40	ΔT_{5B} (DT5B) DRAM	25
41	ΔT_7 (DT7) DRAM	39
42 - 78	Not used	00
79	FBDIMM ODT Values	21
80	Not used	00
81	Channel Protocols Supported LSB	02
82	Channel Protocols Supported MSB	00
83	Back-to-Back Access Turnaround Time	20
84	AMB Read Access Delay for DDR2-800	54
85	AMB Read Access Delay for DDR2-667	50
86	AMB Read Access Delay for DDR2-533	44
87	Psi(T-A) AMB	26
88	ΔT_{Idle_0} (DT Idle_0) AMB	3F
89	ΔT_{Idle_1} (DT Idle_1) AMB	50

Product Type		HYS72T512420EFA–25F–C
Organization		**4 GByte**
		×72
		2 Ranks (×4)
Label Code		**PC2–6400F–555**
JEDEC SPD Revision		**Rev. 1.1**
Byte#	**Description**	**HEX**
90	$\Delta T_{\mathrm{Idle_2}}$ (DT Idle_2) AMB	54
91	$\Delta T_{\mathrm{Active_1}}$ (DT Active_1) AMB	57
92	$\Delta T_{\mathrm{Active_2}}$ (DT Active_2) AMB	53
93	ΔT_{L0s} (DT L0s) AMB	00
94 - 97	Not used	00
98	AMB Junction Temperature Maximum (T_{jmax})	11
99	Category Byte	CA
100	Not used	00
101	AMB Personality Bytes: Pre-initialization (1)	D5
102	AMB Personality Bytes: Pre-initialization (2)	60
103	AMB Personality Bytes: Pre-initialization (3)	08
104	AMB Personality Bytes: Pre-initialization (4)	02
105	AMB Personality Bytes: Pre-initialization (5)	00
106	AMB Personality Bytes: Pre-initialization (6)	00
107	AMB Personality Bytes: Post-initialization (1)	4C
108	AMB Personality Bytes: Post-initialization (2)	00
109	AMB Personality Bytes: Post-initialization (3)	00
110	AMB Personality Bytes: Post-initialization (4)	00
111	AMB Personality Bytes: Post-initialization (5)	00
112	AMB Personality Bytes: Post-initialization (6)	00
113	AMB Personality Bytes: Post-initialization (7)	00
114	AMB Personality Bytes: Post-initialization (8)	00
115	AMB Manufacturers JEDEC ID Code LSB	85
116	AMB Manufacturers JEDEC ID Code MSB	51
117	DIMM Manufacturers JEDEC ID Code LSB	85
118	DIMM Manufacturers JEDEC ID Code MSB	51
119	Module Manufacturing Location	xx
120	Module Manufacturing Date Year	xx
121	Module Manufacturing Date Week	xx
122 - 125	Module Serial Number	xx
126	Cyclical Redundancy Code LSB	0E
127	Cyclical Redundancy Code MSB	0E

Product Type		HYS72T512420EFA–25F–C
Organization		4 GByte
		×72
		2 Ranks (×4)
Label Code		PC2–6400F–555
JEDEC SPD Revision		Rev. 1.1
Byte#	**Description**	**HEX**
128	Module Product Type, Char #1	37
129	Module Product Type, Char #2	32
130	Module Product Type, Char #3	54
131	Module Product Type, Char #4	35
132	Module Product Type, Char #5	31
133	Module Product Type, Char #6	32
134	Module Product Type, Char #7	34
135	Module Product Type, Char #8	32
136	Module Product Type, Char #9	30
137	Module Product Type, Char #10	45
138	Module Product Type, Char #11	46
139	Module Product Type, Char #12	41
140	Module Product Type, Char #13	32
141	Module Product Type, Char #14	35
142	Module Product Type, Char #15	46
143	Module Product Type, Char #16	43
144	Module Product Type, Char #17	20
145	Module Product Type, Char #18	20
146	Module Revision Code	2x
147	Test Program Revision Code	xx
148	DRAM Manufacturers JEDEC ID Code LSB	85
149	DRAM Manufacturers JEDEC ID Code MSB	51
150	informal AMB content revision tag (MSB)	43
151	informal AMB content revision tag (LSB)	10
152 - 175	Not used	00
176 - 255	Blank for customer use	FF

TABLE 17
PC2–5300–555

Product Type		**HYS72T512420EFA–3S–C**
Organization		**4 GByte**
		×72
		2 Ranks (×4)
Label Code		**PC2–5300F–555**
JEDEC SPD Revision		**Rev. 1.1**
Byte#	**Description**	**HEX**
0	SPD Size CRC / Total / Used	92
1	SPD Revision	11
2	Key Byte / DRAM Device Type	09
3	Voltage Level of this Assembly	12
4	SDRAM Addressing	49
5	Module Physical Attributes	23
6	Module Type	07
7	Module Organization	10
8	Fine Timebase (FTB) Dividend and Divisor	00
9	Medium Timebase (MTB) Dividend	01
10	Medium Timebase (MTB) Divisor	04
11	$t_{CK.MIN}$ (min. SDRAM Cycle Time)	0C
12	$t_{CK.MAX}$ (max. SDRAM Cycle Time)	20
13	CAS Latencies Supported	33
14	$t_{CAS.MIN}$ (min. CAS Latency Time)	3C
15	Write Recovery Values Supported (WR)	42
16	$t_{WR.MIN}$ (Write Recovery Time)	3C
17	Write Latency Times Supported	72
18	Additive Latency Times Supported	50
19	$t_{RCD.MIN}$ (min. RAS# to CAS# Delay)	3C
20	$t_{RRD.MIN}$ (min. Row Active to Row Active Delay)	1E
21	$t_{RP.MIN}$ (min. Row Precharge Time)	3C
22	t_{RAS} and t_{RC} Extension	00
23	$t_{RAS.MIN}$ (min. Active to Precharge Time)	B4
24	$t_{RC.MIN}$ (min. Active to Active / Refresh Time)	F0
25	$t_{RFC.MIN}$ LSB (min. Refresh Recovery Time Delay)	FE
26	$t_{RFC.MIN}$ MSB (min. Refresh Recovery Time Delay)	01
27	$t_{WTR.MIN}$ (min. Internal Write to Read Cmd Delay)	1E
28	$t_{RTP.MIN}$ (min. Internal Read to Precharge Cmd Delay)	1E
29	Burst Lengths Supported	03

Product Type		**HYS72T512420EFA–3S–C**
Organization		**4 GByte**
		×72
		2 Ranks (×4)
Label Code		**PC2–5300F–555**
JEDEC SPD Revision		**Rev. 1.1**
Byte#	**Description**	**HEX**
30	Terminations Supported	07
31	Drive Strength Supported	01
32	t_{REFI} (avg. SDRAM Refresh Period)	C2
33	$T_{CASE.MAX}$ Delta / ΔT_{4R4W} Delta	56
34	Psi(T-A) DRAM	60
35	ΔT_0 (DT0) DRAM	3C
36	ΔT_{2Q} (DT2Q) DRAM	24
37	ΔT_{2P} (DT2P) DRAM	2B
38	ΔT_{3N} (DT3N) DRAM	28
39	ΔT_{4R} (DT4R) / ΔT_{4R4W} Sign (DT4R4W) DRAM	42
40	ΔT_{5B} (DT5B) DRAM	24
41	ΔT_7 (DT7) DRAM	2C
42 - 78	Not used	00
79	FBDIMM ODT Values	22
80	Not used	00
81	Channel Protocols Supported LSB	02
82	Channel Protocols Supported MSB	00
83	Back-to-Back Access Turnaround Time	10
84	AMB Read Access Delay for DDR2-800	54
85	AMB Read Access Delay for DDR2-667	50
86	AMB Read Access Delay for DDR2-533	44
87	Psi(T-A) AMB	26
88	ΔT_{Idle_0} (DT Idle_0) AMB	3F
89	ΔT_{Idle_1} (DT Idle_1) AMB	50
90	ΔT_{Idle_2} (DT Idle_2) AMB	54
91	ΔT_{Active_1} (DT Active_1) AMB	57
92	ΔT_{Active_2} (DT Active_2) AMB	53
93	ΔT_{L0s} (DT L0s) AMB	00
94 - 97	Not used	00
98	AMB Junction Temperature Maximum (T_{jmax})	11
99	Category Byte	CA
100	Not used	00
101	AMB Personality Bytes: Pre-initialization (1)	D5

Product Type		HYS72T512420EFA–3S–C
Organization		4 GByte
		×72
		2 Ranks (×4)
Label Code		PC2–5300F–555
JEDEC SPD Revision		Rev. 1.1
Byte#	Description	HEX
102	AMB Personality Bytes: Pre-initialization (2)	60
103	AMB Personality Bytes: Pre-initialization (3)	08
104	AMB Personality Bytes: Pre-initialization (4)	02
105	AMB Personality Bytes: Pre-initialization (5)	00
106	AMB Personality Bytes: Pre-initialization (6)	00
107	AMB Personality Bytes: Post-initialization (1)	4C
108	AMB Personality Bytes: Post-initialization (2)	00
109	AMB Personality Bytes: Post-initialization (3)	00
110	AMB Personality Bytes: Post-initialization (4)	00
111	AMB Personality Bytes: Post-initialization (5)	00
112	AMB Personality Bytes: Post-initialization (6)	00
113	AMB Personality Bytes: Post-initialization (7)	00
114	AMB Personality Bytes: Post-initialization (8)	00
115	AMB Manufacturers JEDEC ID Code LSB	85
116	AMB Manufacturers JEDEC ID Code MSB	51
117	DIMM Manufacturers JEDEC ID Code LSB	85
118	DIMM Manufacturers JEDEC ID Code MSB	51
119	Module Manufacturing Location	xx
120	Module Manufacturing Date Year	xx
121	Module Manufacturing Date Week	xx
122 - 125	Module Serial Number	xx
126	Cyclical Redundancy Code LSB	25
127	Cyclical Redundancy Code MSB	29
128	Module Product Type, Char #1	37
129	Module Product Type, Char #2	32
130	Module Product Type, Char #3	54
131	Module Product Type, Char #4	35
132	Module Product Type, Char #5	31
133	Module Product Type, Char #6	32
134	Module Product Type, Char #7	34
135	Module Product Type, Char #8	32
136	Module Product Type, Char #9	30

Product Type		HYS72T512420EFA–3S–C
Organization		4 GByte
		×72
		2 Ranks (×4)
Label Code		PC2–5300F–555
JEDEC SPD Revision		Rev. 1.1
Byte#	Description	HEX
137	Module Product Type, Char #10	45
138	Module Product Type, Char #11	46
139	Module Product Type, Char #12	41
140	Module Product Type, Char #13	33
141	Module Product Type, Char #14	53
142	Module Product Type, Char #15	43
143	Module Product Type, Char #16	20
144	Module Product Type, Char #17	20
145	Module Product Type, Char #18	20
146	Module Revision Code	0x
147	Test Program Revision Code	xx
148	DRAM Manufacturers JEDEC ID Code LSB	85
149	DRAM Manufacturers JEDEC ID Code MSB	51
150	informal AMB content revision tag (MSB)	43
151	informal AMB content revision tag (LSB)	10
152 - 175	Not used	00
176 - 255	Blank for customer use	FF

7 Package Outline

All Components are surface mounted on one or both sides of the PCB and positioned on the PCB to meet the minimum and maximum trace lengths required for DDR2 SDRAM signals. Bypass capacitors for DDR2 SDRAM devices are located near the device power pins. The AMB device in the center of the DIMM has a metal Heat Sink.

TABLE 18
Raw Card Reference

JEDEC Raw Card	PCB		Dimensions			
			Width [mm]	Height [mm]	Thickness [mm]	Notes
R/C Z	L-DIM-240-36	Figure 4	133.35	30.35	8.2	1)2)3)4)5)

1) Thickness includes Heat Sink. Some early production modules with Heatspreader may be thicker up to 8.2mm.
2) Please contact your sales or marketing representative for more details on package dimensions
3) Drawing according to ISO 8015.
4) Dimensions in mm.
5) General tolerances +/- 0.15.

***Attention:** Heat Sink heat up during operation. When unplugging a DIMM from a system direct skin contact should be avoided until the Heat Sink has reached room temperature.*

***Attention:** The Heat Sink is mechanically loaded. Do not remove. Removal of the clip may cause injuries.*

***Attention:** Any mechanical stress on the Heat Sink should be avoided. Touching the Heat Sink while plugging or unplugging the module may permanently damage the DIMM.*

FIGURE 4

Package Outline L-DIM-240-36 with Full Module Heat Sink

- Drawing according to ISO 8015
- General tolerances ±0.15
- Dimensions in mm

8 DDR2 Nomenclature

TABLE 19
Nomenclature Fields and Examples

Example for	Field Number										
	1	**2**	**3**	**4**	**5**	**6**	**7**	**8**	**9**	**10**	**11**
Micro-DIMM	HYS	64	T	64	0	2	0	K	M	–5	–A
DDR2 DRAM	HYB	18	T	512	16		0	A	C	–5	

TABLE 20
DDR2 DIMM Nomenclature

Field	Description	Values	Coding
1	Module Prefix	HYS	Constant
2	Module Data Width [bit]	64	Non-ECC
		72	ECC
3	DRAM Technology	T	DDR2
4	Memory Density per I/O [Mbit]; Module Density[1)]	32	256 MByte
		64	512 MByte
		128	1 GByte
		256	2 GByte
		512	4 GByte
5	Raw Card Generation	0 .. 9	Look up table
6	Number of Module Ranks	0, 2, 4	1, 2, 4
7	Product Variations	0 .. 9	Look up table
8	Package, Lead-Free Status	A .. Z	Look up table
9	Module Type	D	SO-**D**IMM
		M	**M**icro-DIMM
		R	**R**egistered
		U	**U**nbuffered
		F	**F**ully Buffered
10	Speed Grade	–25F	PC2–6400 5–5–5
		–2.5	PC2–6400 6–6–6
		–3	PC2–5300 4–4–4
		–3S	PC2–5300 5–5–5
		–3.7	PC2–4200 4–4–4
		–5	PC2–3200 3–3–3

Field	Description	Values	Coding
11	Die Revision	–A	First
		–B	Second

1) Multiplying “Memory Density per I/O” with “Module Data Width” and dividing by 8 for Non-ECC and 9 for ECC modules gives the overall module memory density in MBytes as listed in column “Coding”.

TABLE 21
DDR2 DRAM Nomenclature

Field	Description	Values	Coding
1	Component Prefix	HYB	Constant
2	Interface Voltage [V]	18	SSTL_18
3	DRAM Technology	T	DDR2
4	Component Density [Mbit]	256	256 Mbit
		512	512 Mbit
		1G	1 Gbit
		2G	2 Gbit
5+6	Number of I/Os	40	×4
		80	×8
		16	×16
7	Product Variations	0 .. 9	Look up table
8	Die Revision	A	First
		B	Second
9	Package, Lead-Free Status	C	FBGA, Lead-containing
		F	FBGA, lead-free
10	Speed Grade	–25F	DDR2-800 5-5-5
		–2.5	DDR2-800 6-6-6
		–3	DDR2-667 4-4-4
		–3S	DDR2-667 5-5-5
		–3.7	DDR2-533 4-4-4
		–5	DDR2-400 3-3-3

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